IPC ASSOCIATION CON ELECTRONICS INC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier In	formation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-17				
Contact Name	2	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-	-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Product-Env-	-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Re	Requester Item Number M		Mfr Item Number Mfr Item Name			Effectiv		Version	N	Manufacturing Site	We	ight*	UOM	Unit Type
		FDD86567-F085 NMOS DPAK (NMOS DPAK 60V	3.2 mOhm	nOhm 2024-05			P	PBB).36914	mg	Each
	ring Proccess Informa								ï					
2 ,			Terminal Base Alloy J-STD-020 MSL		Rating	Peak Process Body Temperature			Temperature	Numbe	er of Reflow Cyc	eles		
Ma	tte Tin (Sn) - annealed		CU Alloy	1			260		C	30	seconds	3		
omments														
	num time at peak tempera	8												
or more info	rmation regarding materia	l composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.84	mg	Supplier	Silicon (Si)	7440-21-3		1.84	mg
Die Attach Solder	5.37785	mg	Supplier	Silver (Ag)	7440-22-4		0.1344	mg
			A	Lead (Pb)	7439-92-1	7a	4.9745	mg
			Supplier	Tin (Sn)	7440-31-5		0.2689	mg
Lead Frame	145.343		Supplier	Tin (Sn)	7440-31-5		0.2035	mg
			В	Nickel (Ni)	7440-02-0		0.6686	mg
			Supplier	Copper (Cu)	7440-50-8		144.4709	mg
Mold Compound-Black	105.876			Epoxy resin	proprietary data		6.3526	mg
			Supplier	Phenolic Resin	Proprietary Data		6.3526	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5294	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		89.9946	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		2.6469	mg
Plating	1.092	mg	Supplier	Tin (Sn)	7440-31-5		1.092	mg
Wire Bond - Al	0.840288	mg	Supplier	Aluminum (Al)	7429-90-5		0.8403	mg